

Electronic Patent Application Fee Transmittal

Application Number:	10814049				
Filing Date:	31-Mar-2004				
Title of Invention:	Wafer grinding using an adhesive gel material				
First Named Inventor:	Yew Wee Cheong				
Filer:	Angela Moore Sagalewicz/Heather Adamson				
Attorney Docket Number:	111079-136357				
Filed as Large Entity					
Utility Filing Fees					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:					
Pages:					
Claims:					
Miscellaneous-Filing:					
Petition:					
Patent-Appeals-and-Interference:					
Post-Allowance-and-Post-Issuance:					
Extension-of-Time:					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790